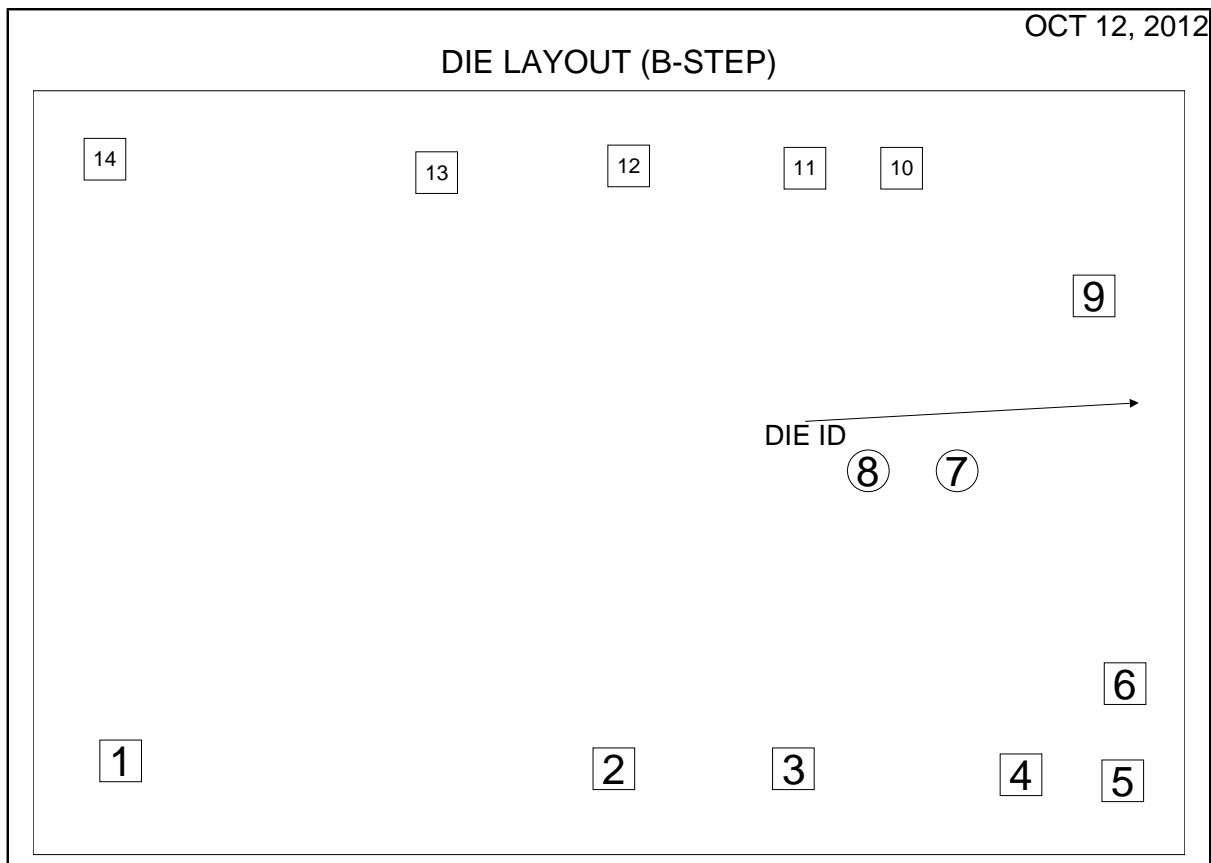


LP2952I-3.3-MDC MCD6010A
ADJUSTABLE MICROPOWER LOW-DROPOUT VOLTAGE REGULATORS



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LP2952B-3.3	Bond Pad Opening Size (min)	89.99 μ m x 89.99 μ m
Die Step	B	Bond Pad Metalization	["AL 0.5%CU"]
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	152mm	Back Side Metal	BAREBACK
Die Size (Drawn)	2489.2 μ m x 1651.0 μ m 98.0mils x 65.0mils	Back Side Connection	Floating or GND
Thickness	304.8 μ m Nominal		
Min Pitch	381.00 μ m		

Note: All values are rounded to the nearest micron.

Special Assembly Requirements:

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Die Bond Pad Coordinate Locations(B-Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X	Y	
OUTPUT	1	-1056	-623	90	x	90
SENSE	2	11	-640	90	x	90
SHUTDOWN	3	399	-640	90	x	90
ERROR	4	891	-653	90	x	90
NC	5	1111	-666	90	x	90
GND	6	1116	-456	90	x	90
NC	7	753	4	90	x	91
NC	8	560	4	91	x	91
NC	9	1049	382	90	x	90
NC	10	633	658	90	x	90
REF	11	424	658	90	x	90
V TAP	12	43	663	90	x	90
FEEDBACK	13	-373	649	90	x	90
INPUT	14	-1089	678	90	x	90

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